

STL27N15

N-CHANNEL 150V - 0.045 Ω - 27A PowerFLAT™ LOW GATE CHARGE STripFET™ MOSFET

TARGET DATA

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TYPE	V _{DSS}	R _{DS(on)}	I _D
STL15N15	150 V	<0.060 Ω	27 A ⁽¹⁾

- TYPICAL $R_{DS}(on) = 0.045 \Omega$
- IMPROVED DIE-TO-FOOTPRINT RATIO
- VERY LOW PROFILE PACKAGE (1mm MAX)
- VERY LOW THERMAL RESISTANCE
- VERY LOW GATE CHARGE



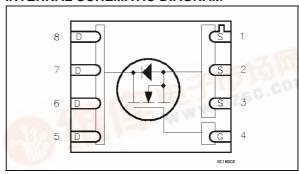
This MOSFET series realized with STMicroelectronics unique "STripFETTM" process has specifically been designed to minimize input capacitance and gate charge. It's therefore suitable as primary switch in advanced high efficiency, high frequency isolated DC-DC converter for telecom an computer application. The new PowerFLATTM package allows e significant reduction in a board space without compromising performance.

APPLICATIONS

- HIGH-EFFICIENCY ISOLATED DC-DC CONVERTERS
- TELECOM AND BATTERY CHARGER ADAPTOR
- SYNCHRONOUS RECTIFICATION



INTERNAL SCHEMATIC DIAGRAM



Ordering Information

f.dzsc.com

SALES TYPE	MARKING	PACKAGE	PACKAGING
STL27N15	L27N15	PowerFLAT	TAPE & REEL

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	150	V
V_{DGR}	Drain-gate Voltage ($R_{GS} = 20 \text{ k}\Omega$)	150	V
V_{GS}	Gate- source Voltage	± 20	V
I _D	Drain Current (continuous) at T _C = 25°C (Steady State)	6	A
I _D	Drain Current (continuous) at T _C = 100°C	4	A
I _{DM} (3)	Drain Current (pulsed)	24	A
P _{tot} (2)	Total Dissipation at T _C = 25°C (Steady State)	4	W
P _{tot} (1)	Total Dissipation at T _C = 25°C	80	W
	Derating Factor	0.03	W/°C
dv/dt (5)	Peak Diode Recovery voltage slope	TBD	V/ns
T _{stg}	Storage Temperature	-55 to 150	°C
Tj	Operating Junction Temperature	-55 to 150	

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STL27N15

THERMAL DATA

Rthj-F	Thermal Resistance Junction-Foot (Drain)	1.56	°C/W
Rthj-pcb(2)	Thermal Operating Junction-pcb	31.2	°C/W

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	100			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	$V_{DS} = Max Rating$ $V_{DS} = Max Rating T_C = 125^{\circ}C$			1 10	μA μA
Igss	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 20 V			±100	nA

ON (6)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$	$I_D = 250 \mu A$	1			٧
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10 V	I _D = 3 A		0.045	0.060	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
gfs (6)	Forward Transconductance	$V_{DS} = 50 \text{ V}$ $I_{D} = 5 \text{ A}$		TBD		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25V$, $f = 1 MHz$, $V_{GS} = 0$		TBD TBD TBD		pF pF pF

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ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Delay Time Rise Time	$\begin{aligned} &V_{DD} = 50 \text{ V} & I_D = 3 \text{ A} \\ &R_G = 4.7 \Omega & V_{GS} = 10 \text{ V} \\ &(\text{Resistive Load, Figure 3}) \end{aligned}$		TBD TBD		ns ns
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V _{DD} = 50V I _D = 6A V _{GS} =10V		TBD TBD TBD	28	nC nC nC

SWITCHING OFF

I	Symbol	Parameter	Test Co	onditions	Min.	Тур.	Max.	Unit
	t _{d(off)} t _f	Turn-off Delay Time Fall Time	V_{DD} = 50 V R_G = 4.7 Ω , (Resistive Load	$I_D = 3 A$ $V_{GS} = 10 V$ d, Figure 3)		TBD TBD		ns ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test Co	onditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain Current Source-drain Current (pulsed)					6 24	A A
V _{SD} (6)	Forward On Voltage	I _{SD} = 3 A	$V_{GS} = 0$			1.2	V
t _{rr} Q _{rr} I _{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	I _{SD} =6 A V _{DD} = 30 V (see test circuit	di/dt = 100A/μs _j = 150°C it, Figure 5)		TBD TBD TBD		ns nC A

⁽¹⁾ The value is rated according R_{thj-F}.
(2) When Mounted on FR-4 board of 1 inch², 2oz Cu
(3) Pulse width limited by safe operating area.
(5) I_{SD} ≤6A, di/dt ≤300A/μs, V_{DD} ≤ V_{(BR)DSS}, T_j ≤ T_{JMAX}.
(6) Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %.

Fig. 1: Unclamped Inductive Load Test Circuit

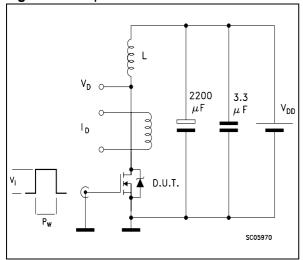


Fig. 3: Switching Times Test Circuits For Resistive Load

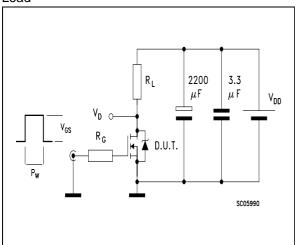


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times

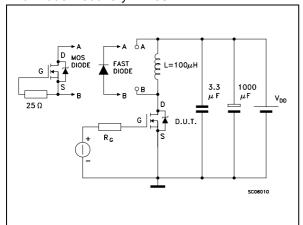


Fig. 2: Unclamped Inductive Waveform

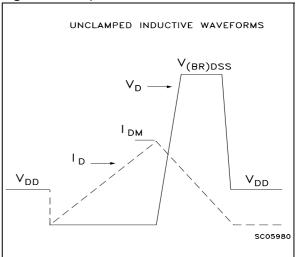
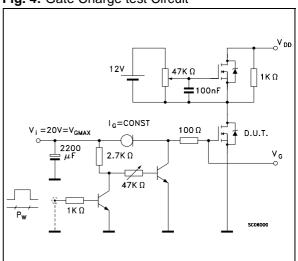


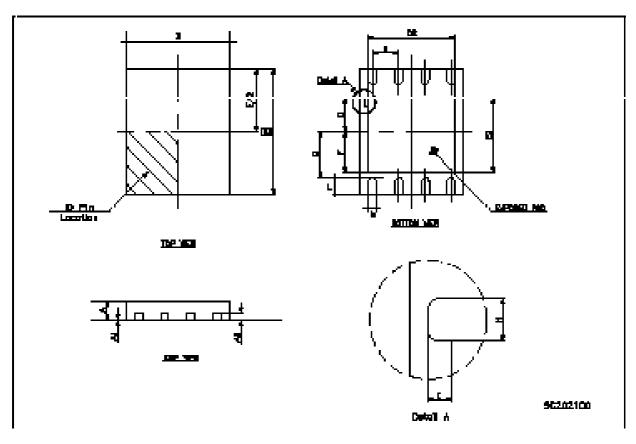
Fig. 4: Gate Charge test Circuit



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PowerFLAT™(6x5) MECHANICAL DATA

DIM.		mm.			inch	
DIM.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	0.80		1.00	0.031		0.039
A1		0.02			0.001	
b	0.35		0.47	0.014		0.018
C		1.61			0.063	
D		5.00			0.197	
D2	4.15		4.25	0.163		0.167
E		6.00			0.236	
Ē2	3.55		3.65	0.140		0.144
e		1.27			0.049	
F		1.99			0.078	
Gi		2.20			0.086	
Н		0,40			0.015	
I		0.219			0.0086	
L	0.70		0.90	0.028		0.035



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